

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-68 (Canceled)

Claim 69 (New): A method of forming a molded surface on a substrate using a stamping tool comprising a translucent portion and an opaque portion, said method comprising:

 pressing said stamping tool into a layer of moldable material on said substrate;
 directing a curing stimulus through said stamping tool, wherein a portion of said moldable material corresponding to said translucent portion is cured and a portion of said moldable material corresponding to said opaque portion is not cured; and
 removing said uncured portion of said moldable material.

Claim 70 (New): The method of claim 69 further comprising repeating said pressing step and said directing step to create a plurality of cured molded surfaces.

Claim 71 (New): The method of claim 70 further comprising forming contact structures at least in part on said molded surfaces.

Claim 72 (New): The method of claim 69, wherein:

 said stamping tool comprises a tooth, said tooth comprising said opaque portion and said translucent portion,

 said opaque portion corresponds to an opening to a surface of said substrate to be formed in said moldable material, and

 said translucent portion corresponds to said molded surface.

Claim 73 (New): The method of claim 72, wherein said stamping tool further comprises:

 a plurality of said teeth, each comprising an opaque portion and a translucent portion, and
 additional opaque portion(s) separating adjacent ones of said teeth.

Claim 74 (New): The method of claim 69, wherein said curing stimulus is ultraviolet light.

Claim 75 (New): The method of claim 69 further comprising forming a contact structure at least in part on said cured portion of said moldable material.

Claim 76 (New): A method of forming a plurality of electrically conductive contact structures on an electronic component comprising a plurality of electrically conductive contact elements, each said contact structure comprising a base connected to one of said contact elements and a beam, said method comprising:

depositing a layer of moldable material on said electronic component;

providing a stamping tool comprising a plurality of protruding regions, a plurality of contoured regions, and a plurality of recessed regions, each said protruding region defining a base of one of said contact structures and corresponding to one of said contact elements on said electronic component, each said contoured region defining a beam of one of said contact structures, and each said recessed region defining a separation between adjacent ones of said contact structures;

aligning said protruding regions of said stamping tool with said contact elements of said electronic component;

pressing said stamping tool into said moldable material, said plurality of protruding regions forming molds in said moldable material of bases of said contact structures, and said plurality of contoured regions forming beam molds in said moldable material of beams of said contact structures; and

depositing contact structure material into said beam molds and said base molds.

Claim 77 (New): The method of claim 76, wherein said step of depositing a layer of moldable material on an electronic component comprises:

placing said electronic component in a mold; and

injecting said moldable material into said mold.

Claim 78 (New): The method of claim 76 further comprising planarizing said layer of moldable material deposited on said electronic component.

Claim 79 (New): The method of claim 76 further comprising heating said stamping tool during said step of pressing said stamping tool into said moldable material.

Claim 80 (New): The method of claim 79 further comprising, after heating said stamping tool, cooling said stamping tool while said stamping tool is pressed into said moldable material.

Claim 81 (New): The method of claim 76 further comprising cooling said stamping tool while said stamping tool is pressed into said moldable material.

Claim 82 (New): The method of claim 76, wherein at least one of said contoured regions comprises a ribbed surface.

Claim 83 (New): The method of claim 76, wherein at least one of said contoured regions comprises a corrugated surface.

Claim 84 (New): The method of claim 76, wherein at least one of said contoured regions is selected from a group consisting of a V shape, a U shape, or a bifurcation.

Claim 85 (New): The method of claim 76 further comprising:

after pressing said stamping tool into said moldable material, removing said stamping tool and depositing a seed layer of conductive material over said moldable material; and

patterning a layer of masking material over said seed layer, wherein patterns in said masking material correspond to pairs of said beam and base molds, and

wherein said contact material is deposited into said molds by depositing said contact material onto said seed layer through said patterns in said masking material.

Claim 86 (New): The method of claim 85 further comprising removing said masking material and said moldable material.

Claim 87 (New): The method of claim 76, wherein said stamping tool further comprises a plurality of reentrant teeth disposed to form a plurality of lips in said moldable material.

Claim 88 (New): The method of claim 87, wherein said moldable material is elastic.

Claim 89 (Withdrawn): The method of claim 76, wherein said step of depositing contact structure material comprises depositing said contact structure material using an electroless deposition process.

Claim 90 (New): The method of claim 76, wherein said electronic component comprises a plurality of dies composing an unsingulated semiconductor wafer.

Claim 91 (New): The method of claim 90, wherein said contact elements are terminals of said dies.

Claim 92 (New): The method of claim 76, wherein said moldable material is selected from a group consisting of polymethylmethacrylates, polycarbonates, polyurethanes, ABS plastics, photoresists, novolac resins, epoxies, and waxes.

Claim 93 (New): The method of claim 76, wherein said moldable material is selected from a group consisting of polymethylmethacrylates, photopolymers, novolac resins, and epoxies.

Claim 94 (New): The method of claim 76, wherein said moldable material comprises a thermoplastic material.